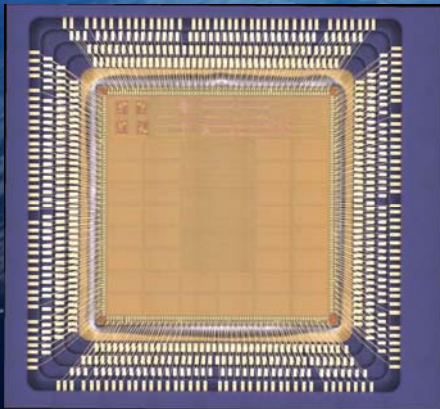


# HPDP-40

High Performance Data Processor –  
A New Generation Space Processor in  
Demonstration

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DEFENCE AND SPACE



**AIRBUS**

# Content

- Introduction
- HPDP-40 Architecture / SW Development
- HPDP-40 Demo Kit
- HPDP-40 Test Status & Power Measurements
- Application Demonstrations
- HPDP-40 Chip Industrialisation
- Conclusion and Outlook

# Introduction

## Introduction

The development of **HPDP** has been initiated by the European Space Agency (ESA) and DLR to address the need for a flexible and re-programmable high performance data processor.

It is being implemented in the 65nm radiation hardened technology of ST Microelectronics (C65SPACE).

Key Advantages of HPDP-40 device:

- Ability to meet the increasing requirements of future payloads regarding flexibility, processing power and re-programmability
- Radiation robustness for all earth orbit and planetary exploration missions
- Low power consumption

# HPDP Architecture & Software Development Flow

## HPDP-40 Architecture (1/2)

HPDP-40 implements the eXtreme Processing Platform (**XPP**), a runtime reconfigurable data processing engine developed by PACT XPP Technologies AG.

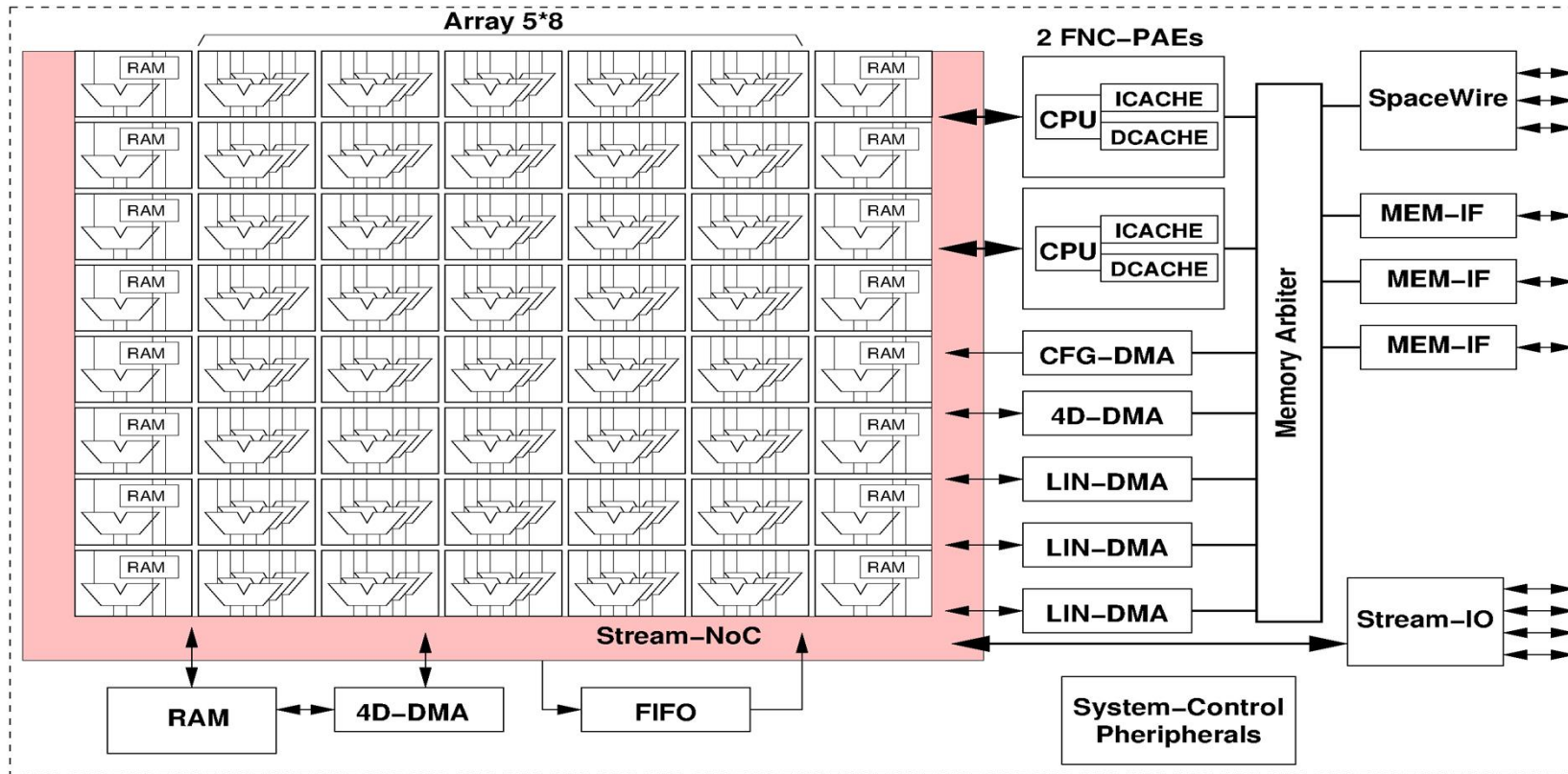
XPP configuration:

- 40 ALU Processing Array Elements (16b) running at 250MHz
- 16 columns RAM blocks for memory
- 2 VLIW processor cores (FNC PAE) running at 125MHz
- Connected by a reconfigurable data and event network

The device provides:

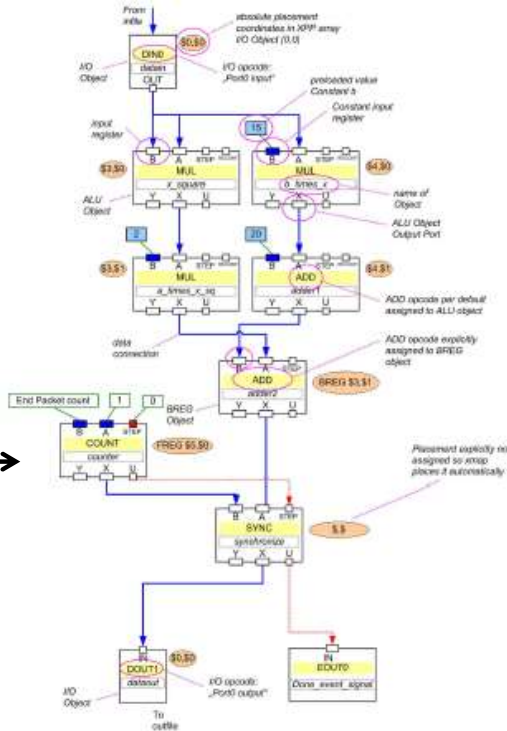
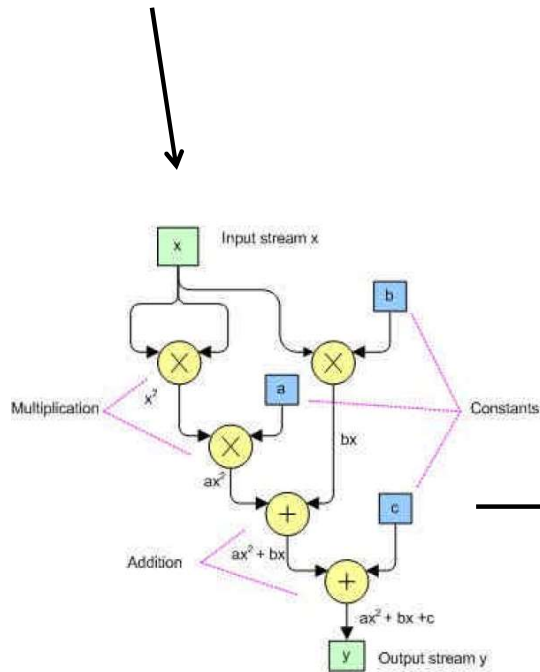
- 40Gops of arithmetic operations through parallelism
- 4x 1.1Gbps Streaming Ports
- >4 Mbyte on-chip SRAM
- Memory protections, Watchdog

# HPDP-40 Architecture (2/2)



# HPDP-40 Software Development Flow

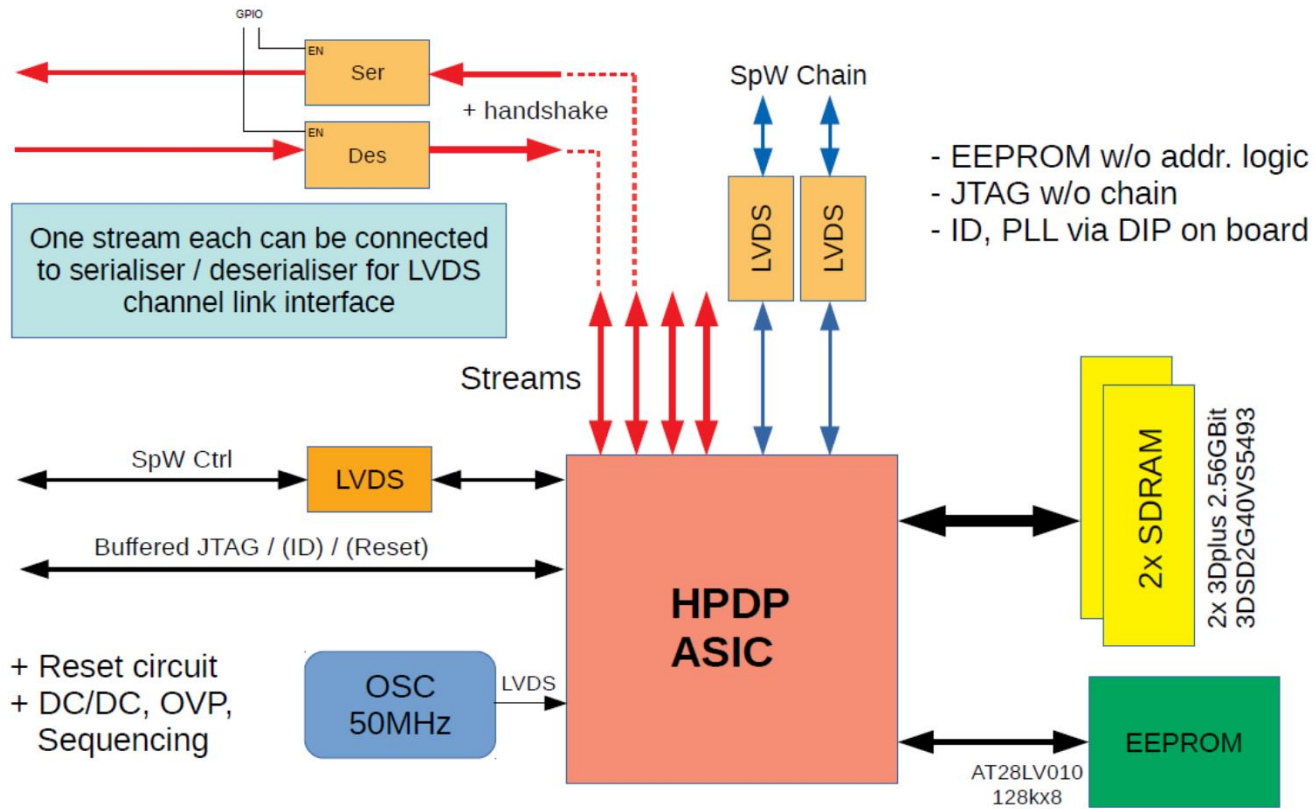
$$y = ax^2 + bx + c.$$



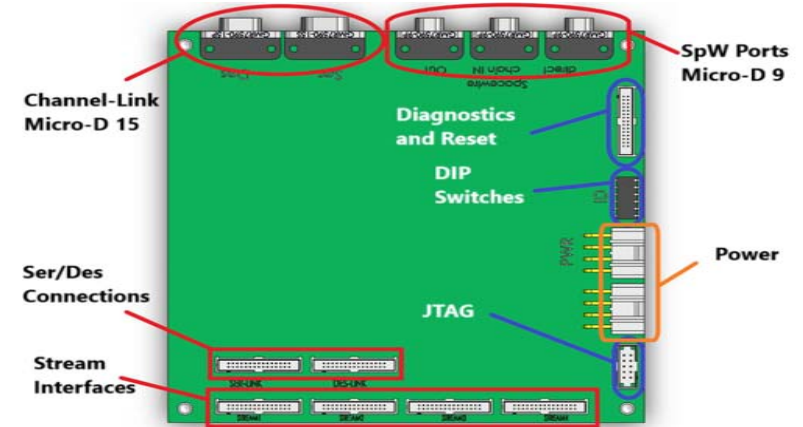
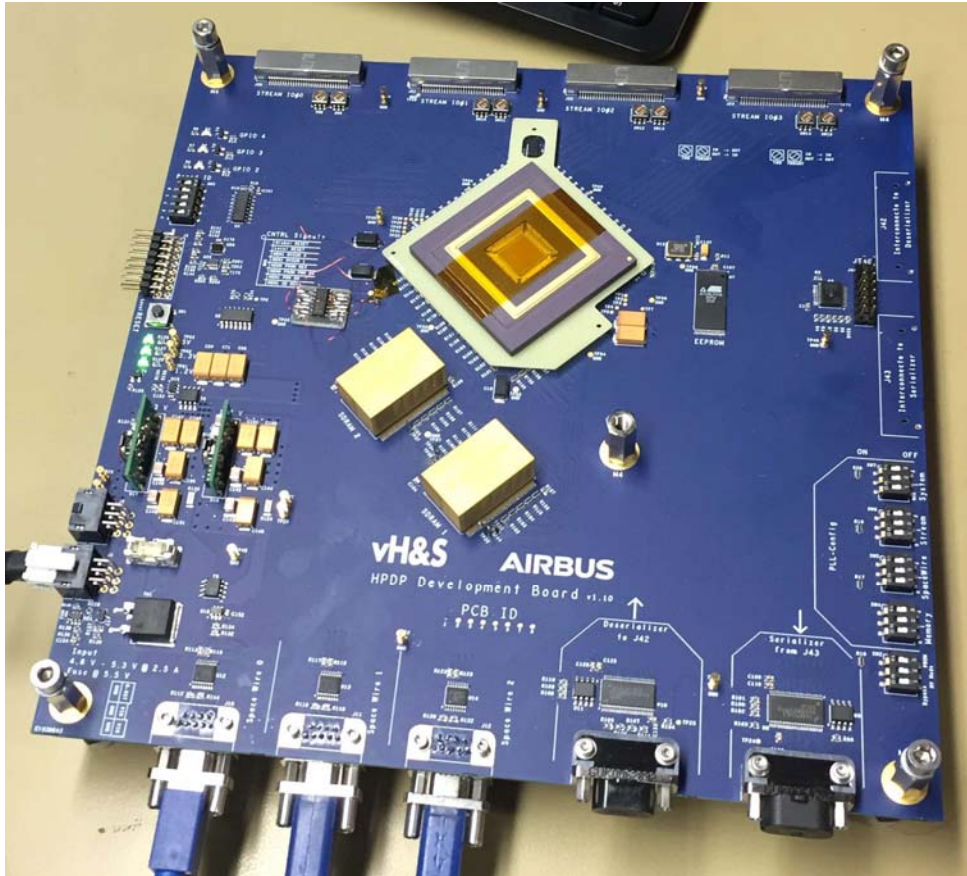


# HPDP-40 Demo Kit

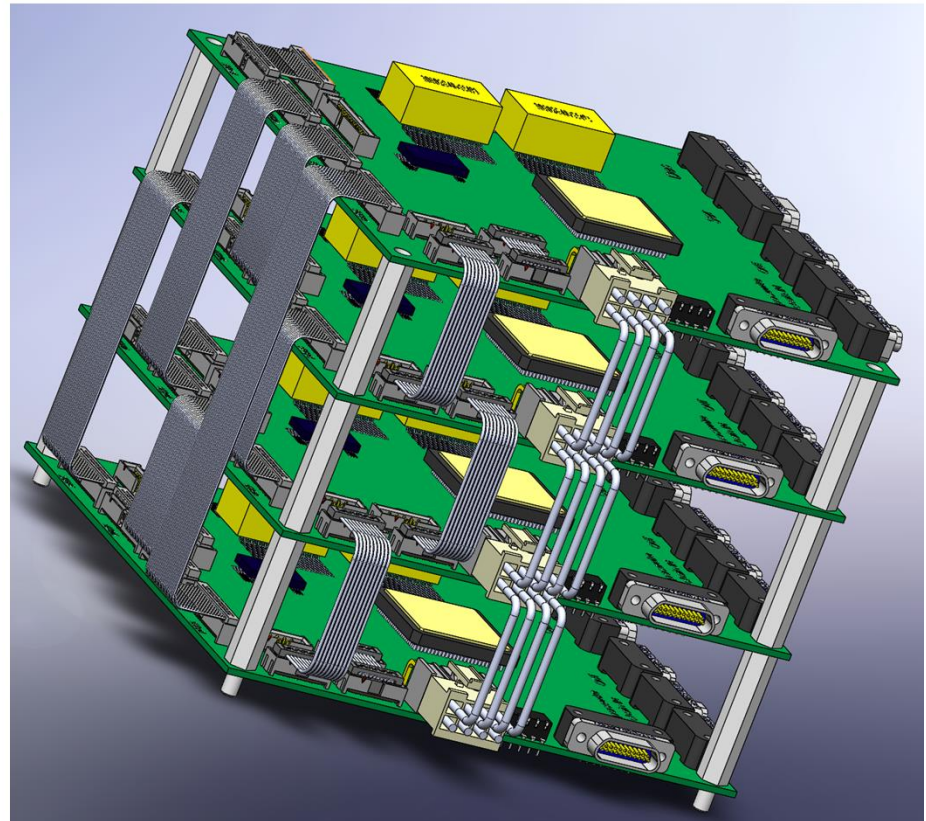
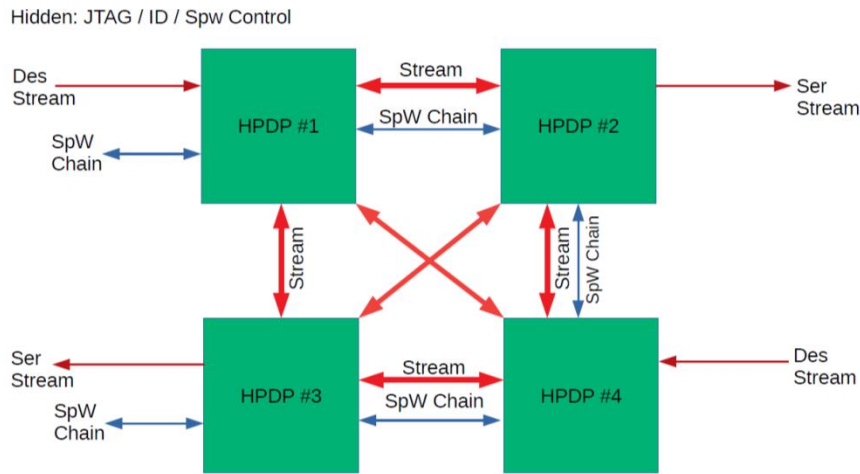
# Demokit (1/3)



# Demokit (2/3)



# Demokit (3/3) - Cascading



# Test Status & Power Management



## HPDP Test Status & Power Measurements (1/2)

Tests are being carried out involving the following sub-systems:

- √ SpW Interface (for Remote Booting)
- √ 2 FNC Execution @125MHz
- √ Port 0 Memory Interface (Non-Volatile Memory)
- √ Port 1 Memory Interface (SDRAM)
- √ On-Chip SRAM
- √ Array Configuration @250MHz
- √ DMAs channels activated

The preliminary power consumption data of the board:

- √ 3.3V domain: stand-by 752mW, running 1.82W
- √ 1.2V domain: stand-by/running 670mW

## HPDP Test Status & Power Measurements (2/2)

### Other Preliminary Tests that have been successfully performed:

- √ Stream I/O
- √ Array configuration capability
- √ Array computational capability
- √ EEPROM R/W capability

### What Remains to be Tested:

- Array Operation/Demonstrations;
- Streaming-I/Os with full speed and with external SERDES devices
- Multi-Board Operation

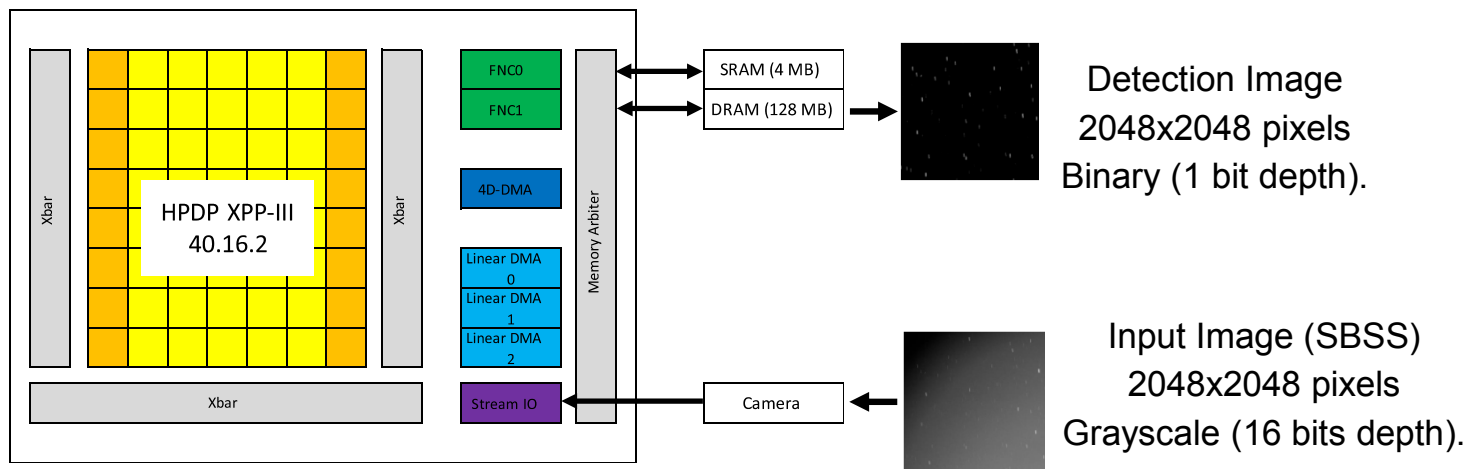
# Application Demonstrations



# Streak observations algorithms to detect space debris (1)

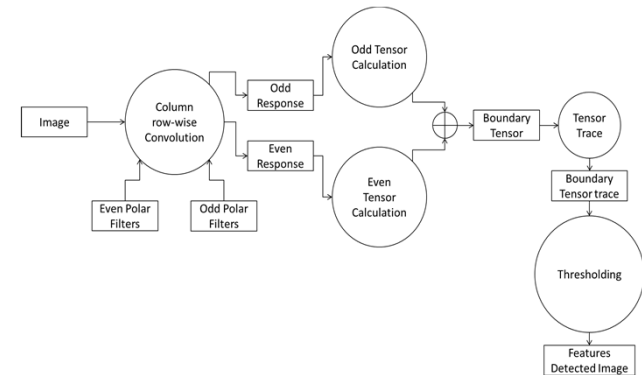
## ✓ Objective:

- ❑ *Performance*: process one image in one second or less.
- ❑ *Portability*: suitability to implement data-flow. .



## Streak observations algorithms to detect space debris (2)

Total memory access Time for the complete algorithm			
Task	Time [sec]	Origin	Destination
transfImg_StreamIOtoDRAM	0,02097	Stream IO	DRAM
transfSubImg_DRAMtoSRAM	0,02097	DRAM	SRAM
boundaryTensor	0,67109	SRAM	SRAM
transfRes_SRAMtoDRAM	0,02097	SRAM	DRAM
<b>Total [sec]</b>	<b>0,734</b>		



Boundary Tensor Flow Block Diagram

⇒ Real-time requirement is met.

Platform	Performance
HPDP	1 image in 0.7s
Desktop PC <sup>1</sup> with algorithm written in C	1 image in 12s

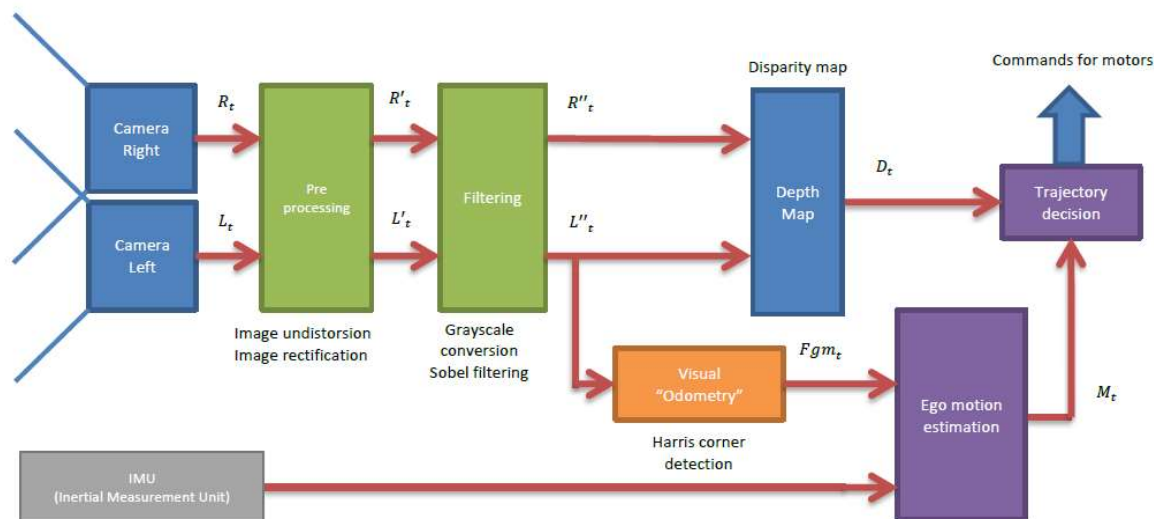
<sup>1</sup>Intel Core i5 Processor clocked at 2.5 GHz with 4 Mbytes of L3 cache

# Autonomous Navigation for Lander Units and Rovers (1)



## ✓ Objective:

- ❑ *Performance*: Processing Chain per image within one second or less
- ❑ *Portability*: suitability to implement data-flow. .














## Autonomous Navigation for Lander Units and Rovers (2)

### ✓ Implementations:

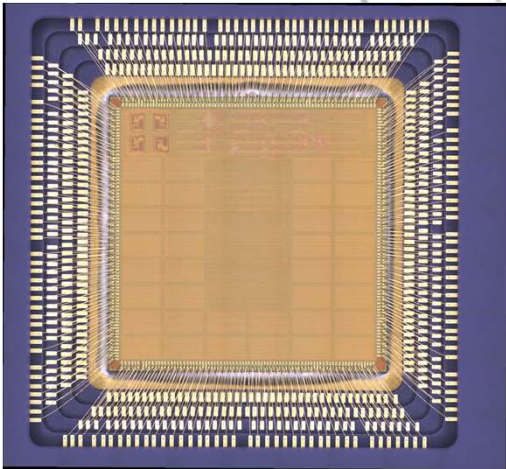
- ❑ *Image Processing Chain executed on HPDP simulator with images of “equivalent” Martian soil*
- ❑ *Pre-processing and Visual Odometry (Harris Corner Detection) can be processed within one second*

### ✓ Next Steps:

- ❑ *Depth Map computation*
- ❑ *Execution on real hardware*
- ❑ *Image compression CCSDS 122.0-B1*

	Right	Left
Raw images (933x468)		
Rectified images (933x468)		
RGB to grayscale (Value method) (933x468)		
Sobel operator (Magnitude gradient) (933x468)		
Harris Corner detection (Right image <sup>1</sup> ) Opacity set to 60%		
	Corners $T_C = 100$	Edges $T_E = -100$
Depth map computation (with Blur)		

# HPDP-40 Chip Industrialisation



## HPDP-40 Industrialisation

Aiming industrialization and QML-V plus delta ESCC qualification the following activities currently carried out or planned within current projects:

- A dedicated exhaustive test plan has been elaborated
- ATPG Test covering >95% coverage
- Burn-in board in development to test at 125C ambient temperature and under worst case bias conditions. The devices will be operational during the test with a sample code running in a loop and the test will last about 1000h.
- Radiation Tests covering both total dose (up to 300krad Si) and heavy ion (up to 88 MeV-cm<sup>2</sup>/mg) experiments
  
- The device is housed in a 625 ceramic PGA package.

# Conclusion & Next Steps

## Conclusion

- ❑ The High Performance Data Processor for Space Applications developed under DLR and ESA contracts is now under commissioning tests in Airbus Ottobrunn and ISD Athens laboratories.
- ❑ Applications have been implemented on the simulator and showed suitability of the architecture.

## Next Steps

- ❑ Porting of applications on the demokit to demonstrate the performance in hardware and show the very efficient power consumption of this architecture.
- ❑ Enforce the industrialization of the chip to fit with the next mission requiring high data processing performance



## Contributors

- Laurent Hili, ESA Technical Officer in the frame of KIPSAT activities (ST 65nm rad hard technology)
- Thierry Scholastique and Francois Martin, STM , HPDP Backend Design
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- George Dramitinos, Yiannis Katelouzos, Olga Dokianaki, Panagiotis Vagiannis, Manolis Lourakis ISD SA
- Vincent Perel, CPE Lyon, Master Student

Thank you